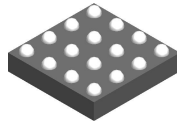


**DATA BOOK
PACKAGE OUTLINE**

DRAFTER:	K. SINCERBOX	DATE:	05/27/2020	DIMENSIONS IN MILLIMETERS	
DESIGNER:		DATE:		 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS CODE IDENTITY NUMBER 01295 ePOD, YCJ0016-C01 / DSBGA, 16 BALL, 0.35 MM PITCH	
CHECKER:	K. SINCERBOX	DATE:	05/27/2020		
ENGINEER:	D. KARRER	DATE:	05/27/2020		
APPROVED:	D. CHIN & J. MARIANO	DATE:	05/27/2020		
RELEASED:	K. SINCERBOX	DATE:	05/27/2020		
TEMPLATE INFO:	EDGE# 4218519	DATE:	04/07/2016	SCALE NTS	SIZE A
				4225953	REV A
					PAGE 1 OF 5

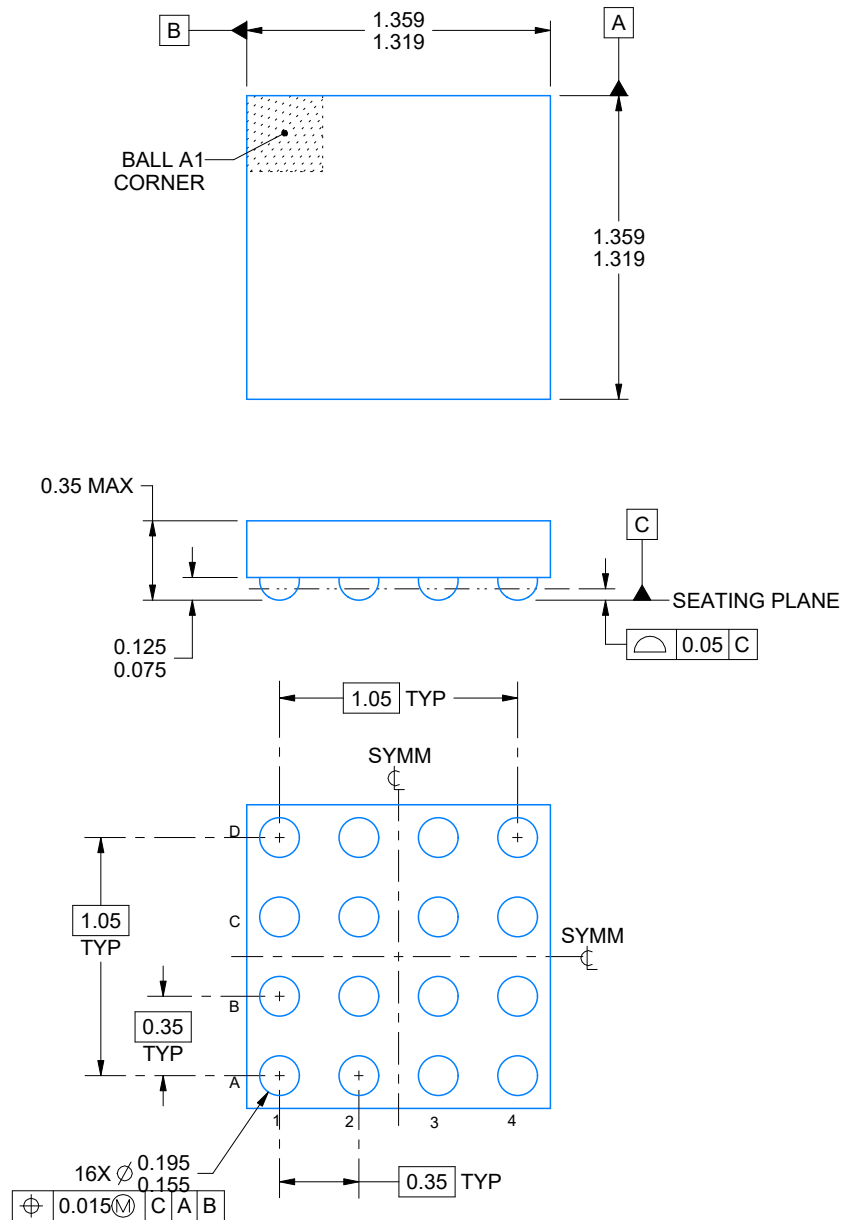
YCJ0016-C01



PACKAGE OUTLINE

DSBGA - 0.35 mm max height

DIE SIZE BALL GRID ARRAY



4225953/A 05/2020

NOTES:

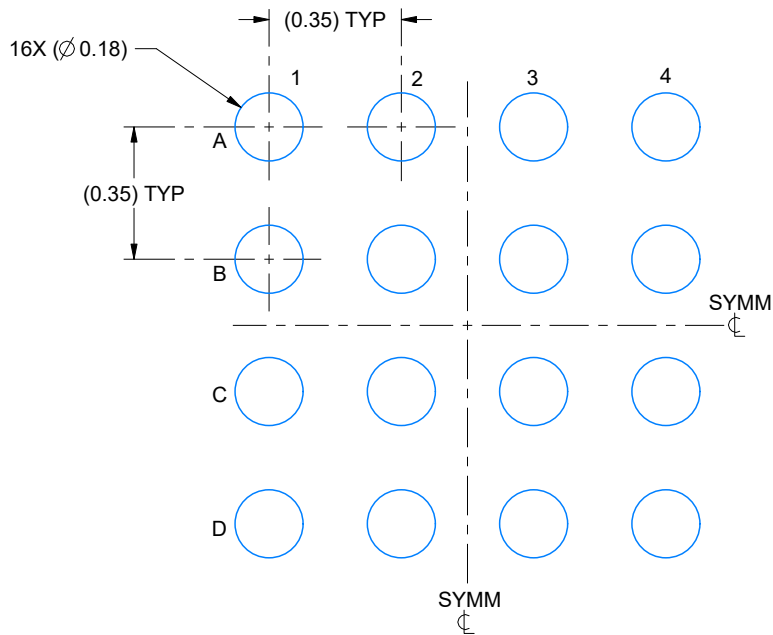
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

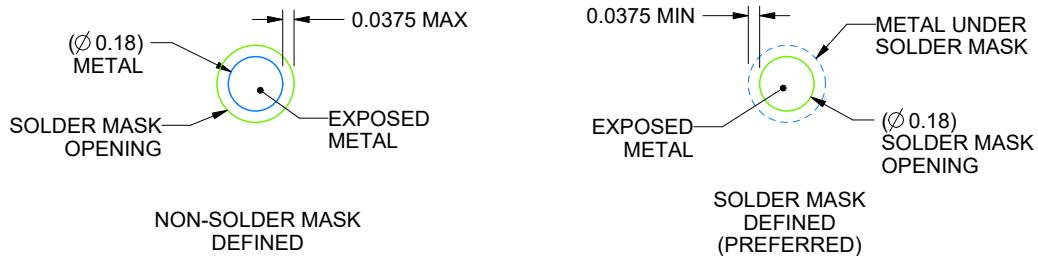
YCJ0016-C01

DSBGA - 0.35 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 50X



SOLDER MASK DETAILS
NOT TO SCALE

4225953/A 05/2020

NOTES: (continued)

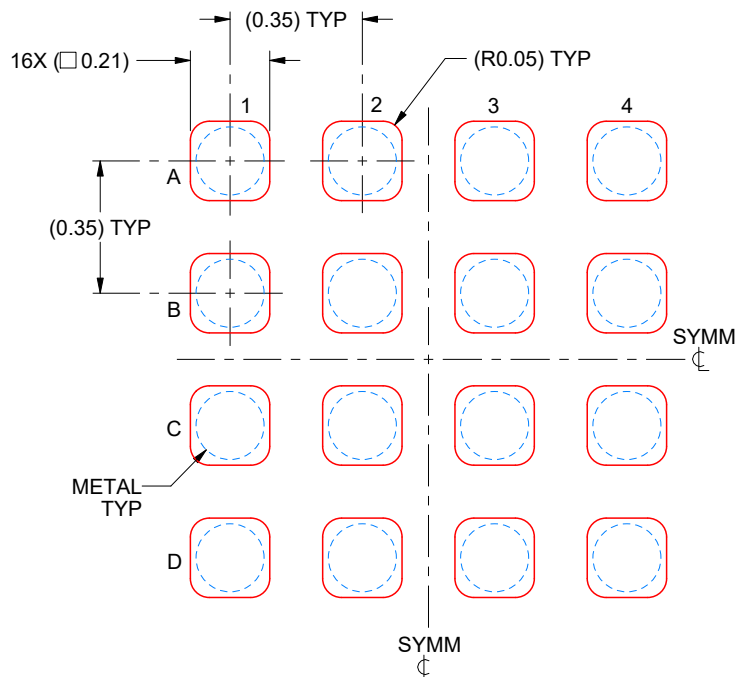
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.
See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YCJ0016-C01

DSBGA - 0.35 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.075 mm THICK STENCIL
SCALE: 50X

4225953/A 05/2020

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2187852	05/27/2020	D. KARRER / K. SINCERBOX